US00D726662S

(12) United States Design Patent
Honda

(10) **Patent No.:** **US D726,662 S**
(45) **Date of Patent:** ** **Apr. 14, 2015**

---

(54) **SOLDERLESS TERMINAL**

(71) Applicant: **Japan Aviation Electronics Industry, Limited**, Tokyo (JP)

(72) Inventor: **Yosuke Honda**, Tokyo (JP)

(73) Assignee: **Japan Aviation Electronics Industry, Limited**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/503,166**

(22) Filed: **Sep. 24, 2014**

(30) **Foreign Application Priority Data**

Apr. 9, 2014 (JP) 2014-007772

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/154**

(58) **Field of Classification Search**
USPC D13/120, 133, 147, 154, 184, 199;
439/567, 636, 660, 844, 849, 850–852,
439/857, 862, 865–867, 870, 877, 884–891
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D605,138 S	*	12/2009	Sogo et al.	D13/154
D618,179 S	*	6/2010	Arai et al.	D13/154
D668,228 S	*	10/2012	Chartrand et al.	D13/154
D672,317 S	*	12/2012	Jibiki	D13/154

FOREIGN PATENT DOCUMENTS

JP	1243264 S	6/2005

* cited by examiner

Primary Examiner — Daniel Bui
(74) *Attorney, Agent, or Firm* — Cermak Nakajima & McGowan LLP; Tomoko Nakajima

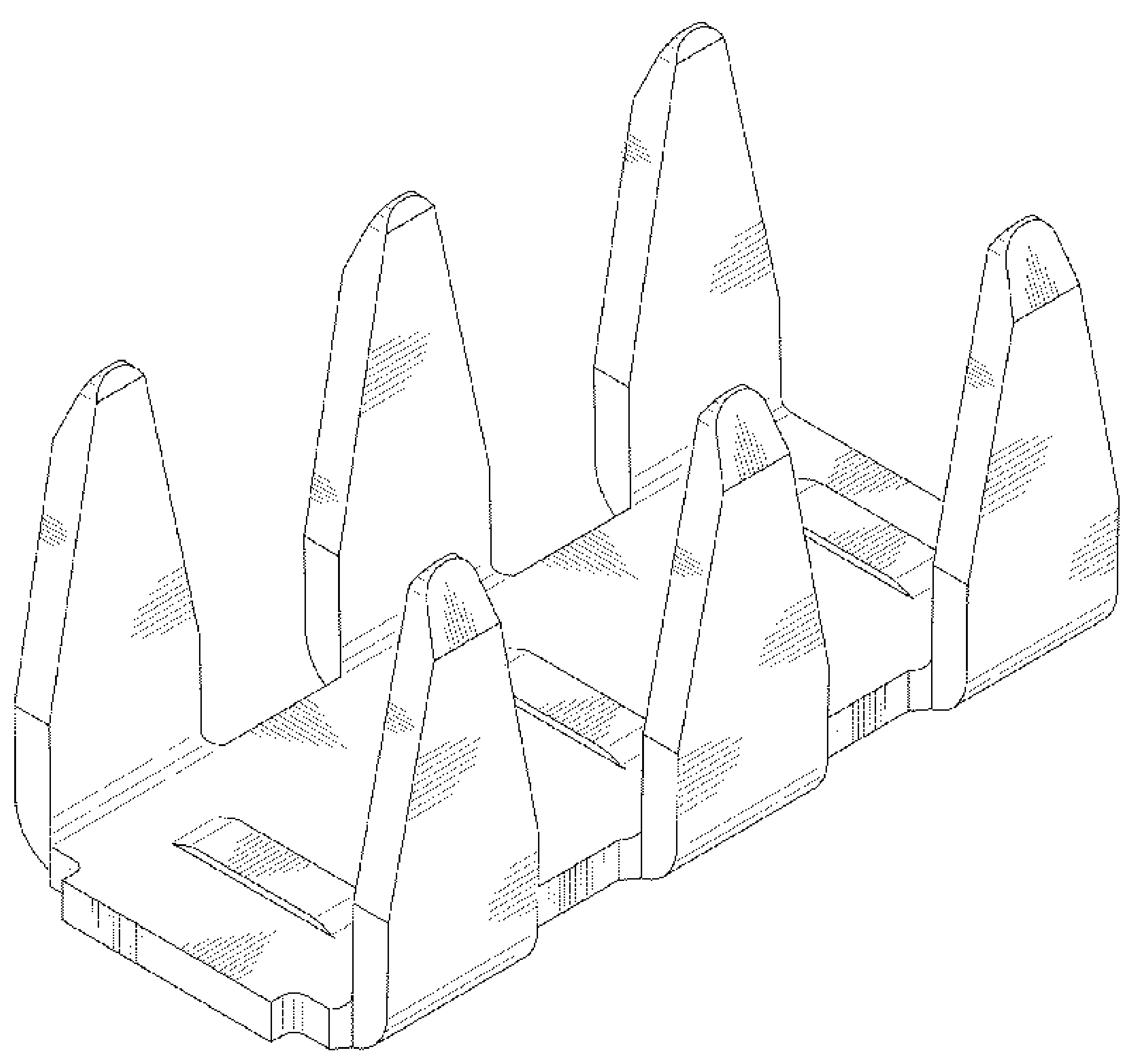
(57) **CLAIM**

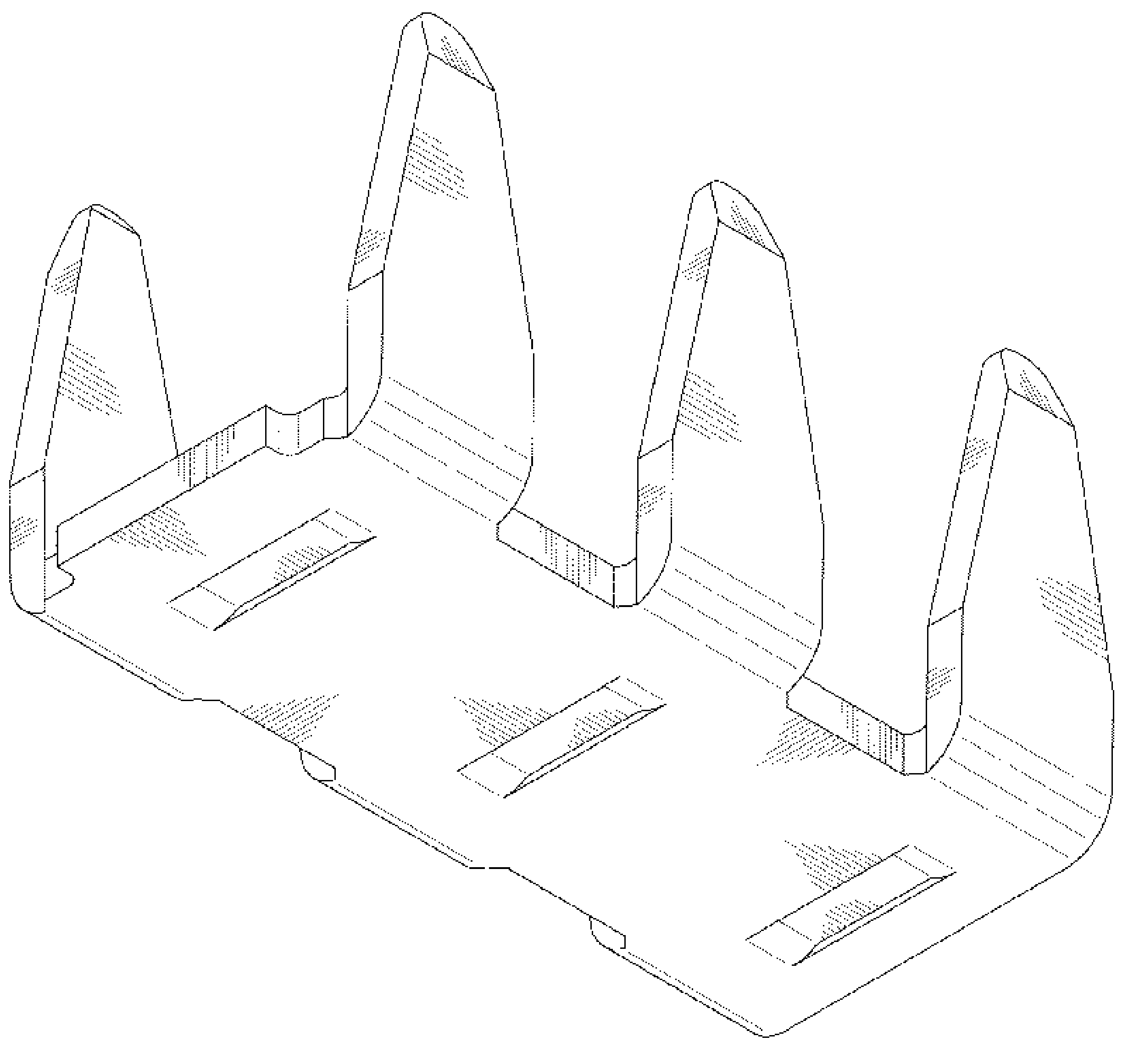
The ornamental design for a solderless terminal, as shown.

DESCRIPTION

FIG. **1** is a front elevational view of a solderless terminal showing my new design;
FIG. **2** is a top plan view thereof;
FIG. **3** is a right side elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a rear elevational view thereof; and
FIG. **6** is a bottom plan view thereof.
FIG. **7** is a top perspective view thereof; and,
FIG. **8** is a bottom perspective view thereof.

1 Claim, 8 Drawing Sheets





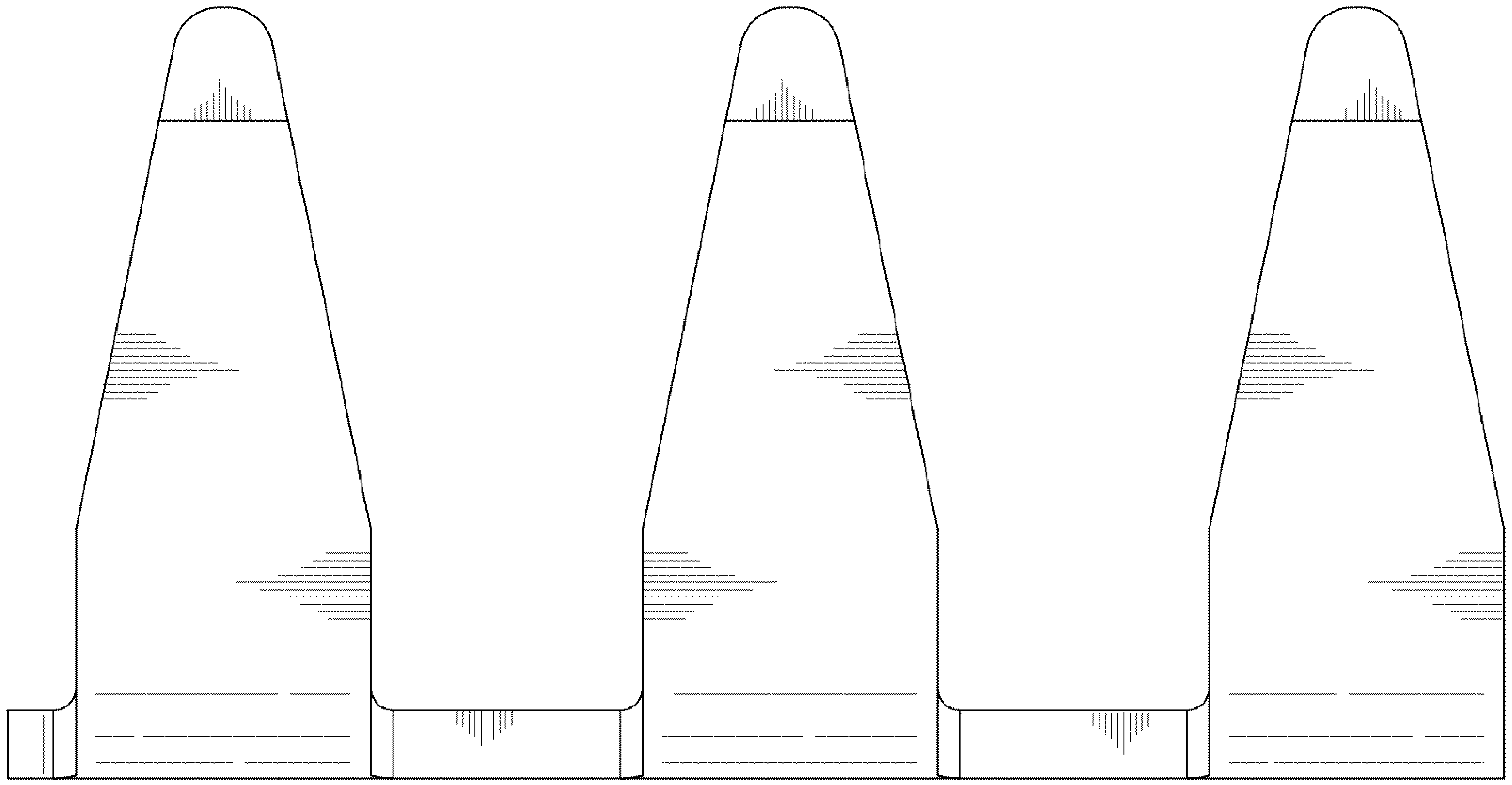


FIG.1

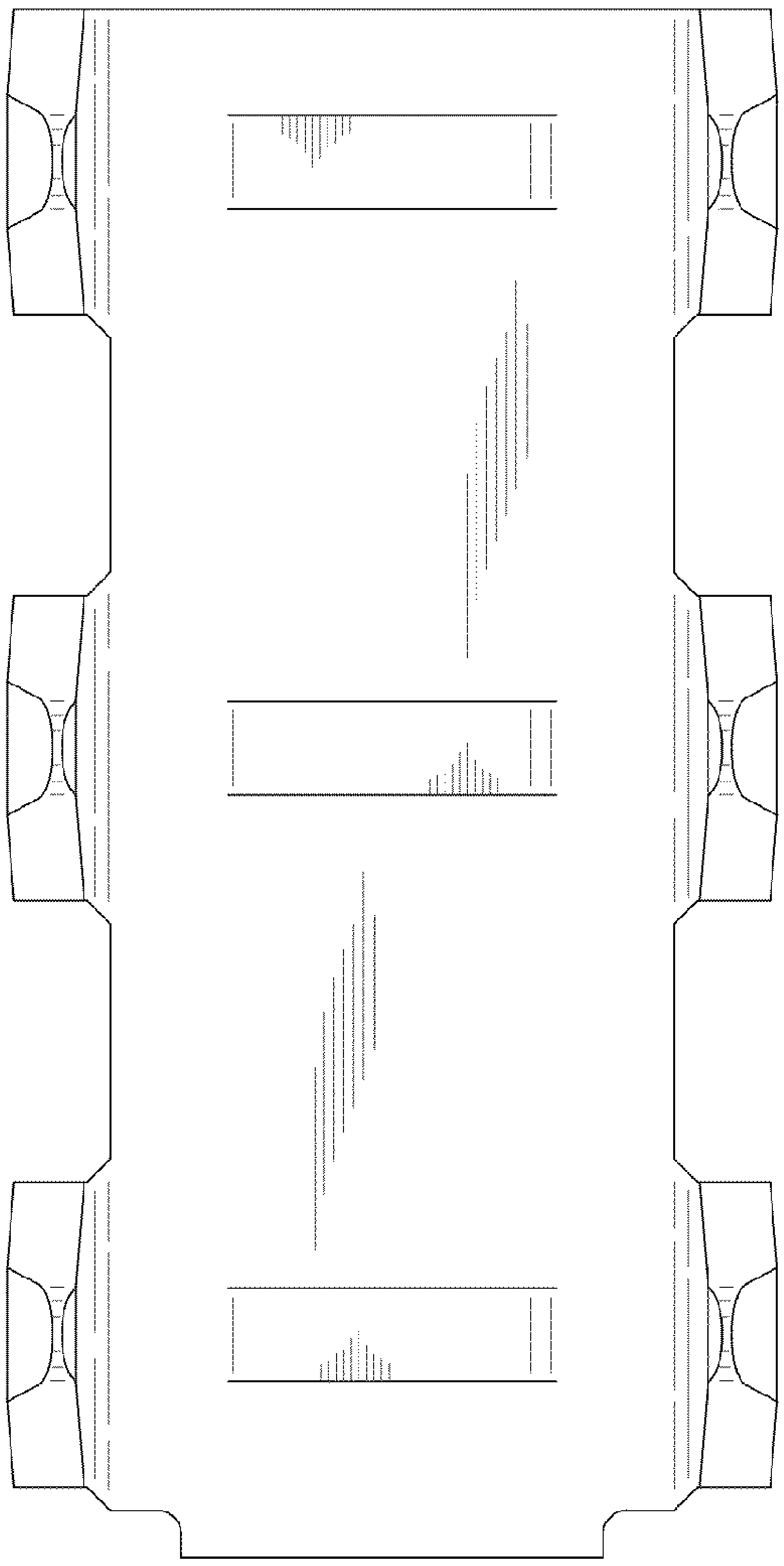


FIG.2

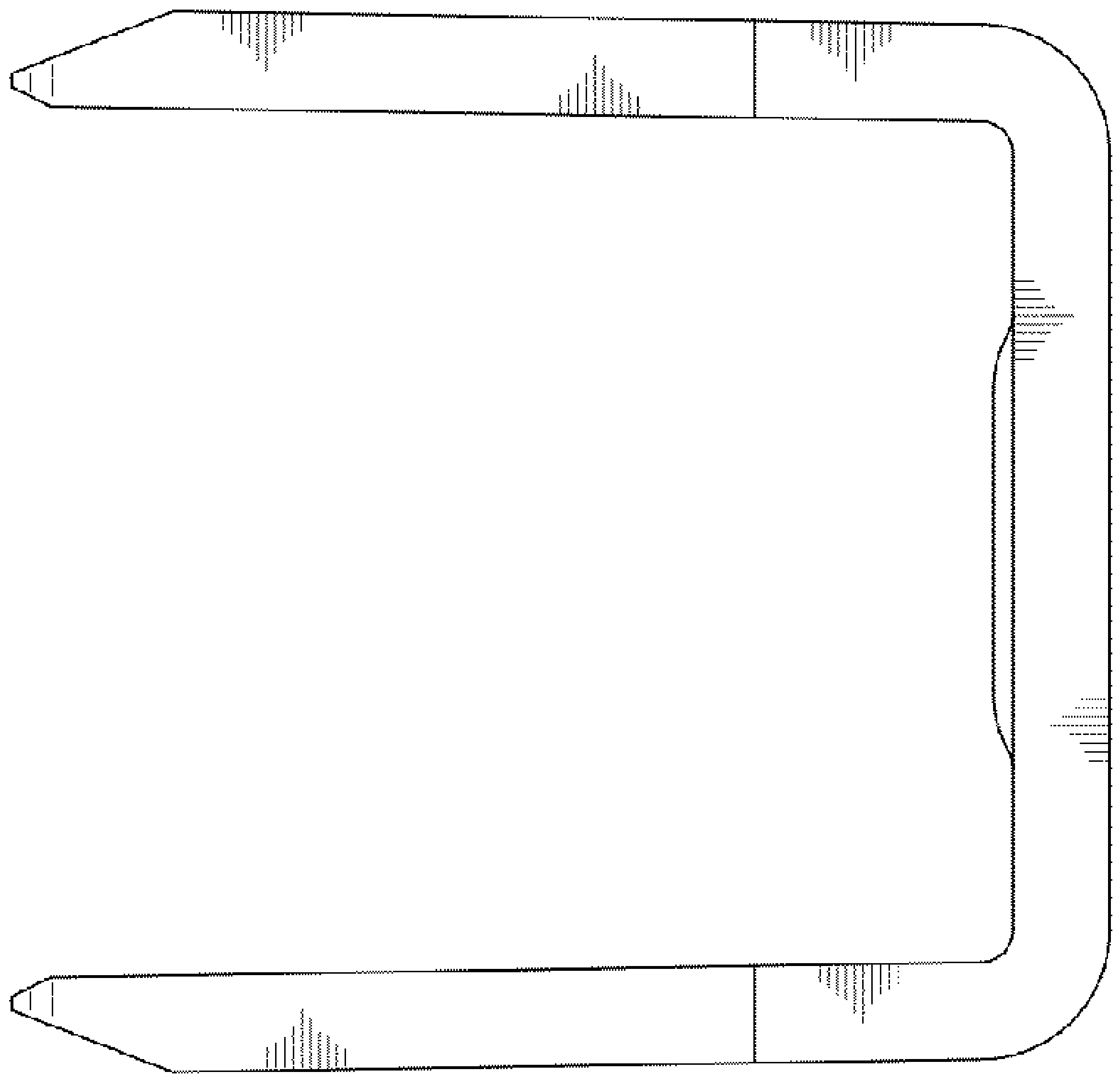


FIG.3

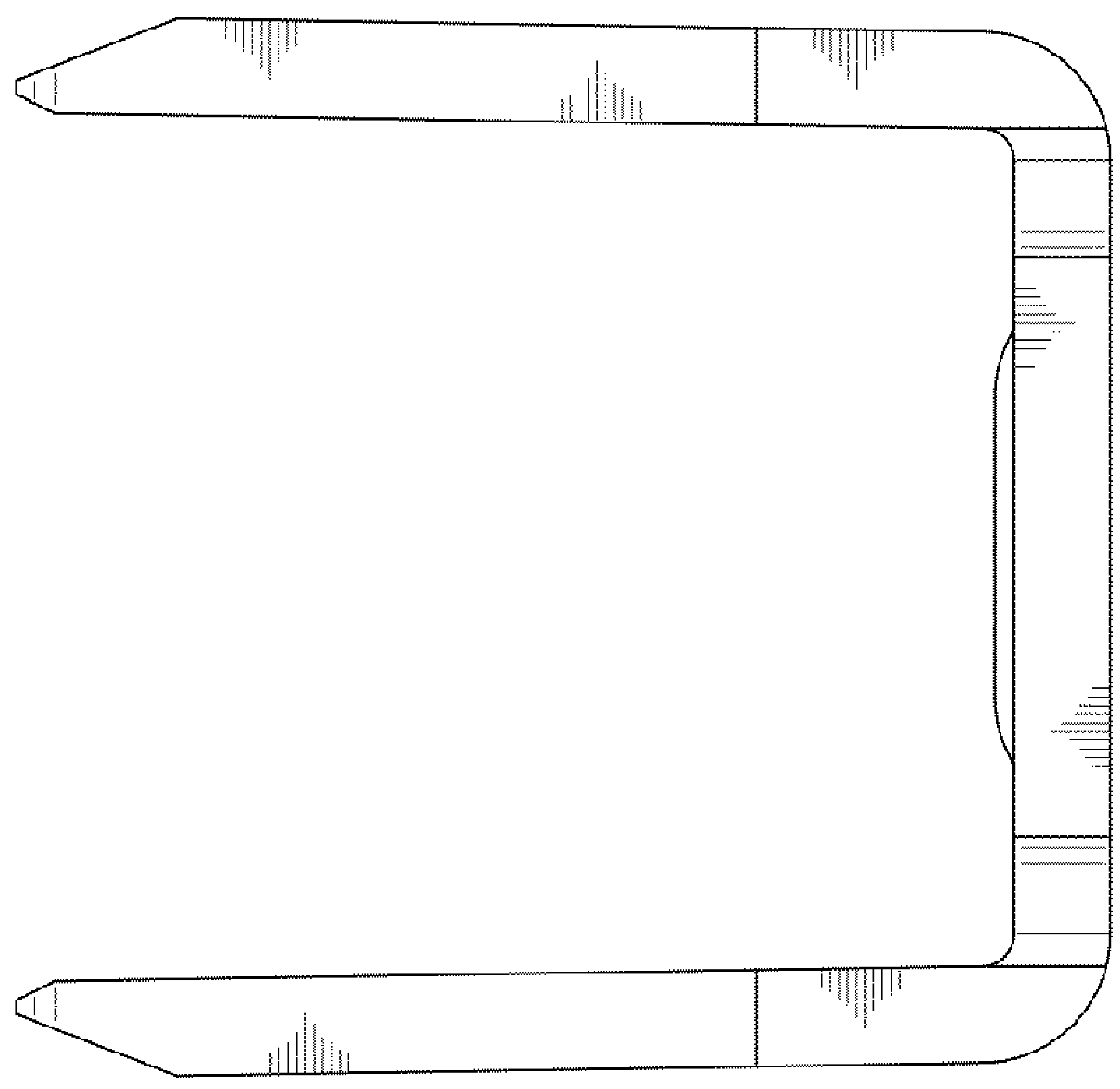


FIG.4

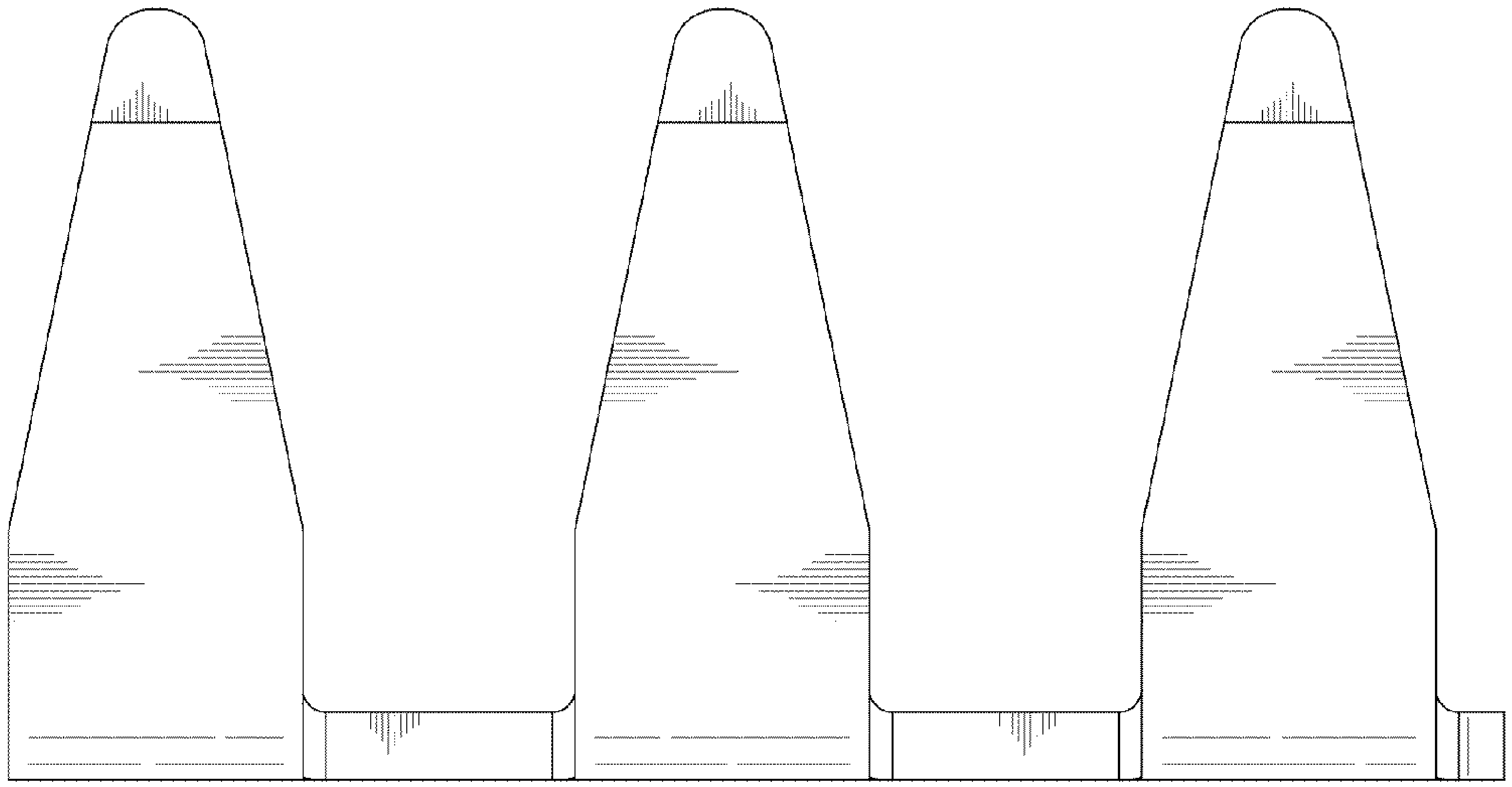


FIG.5

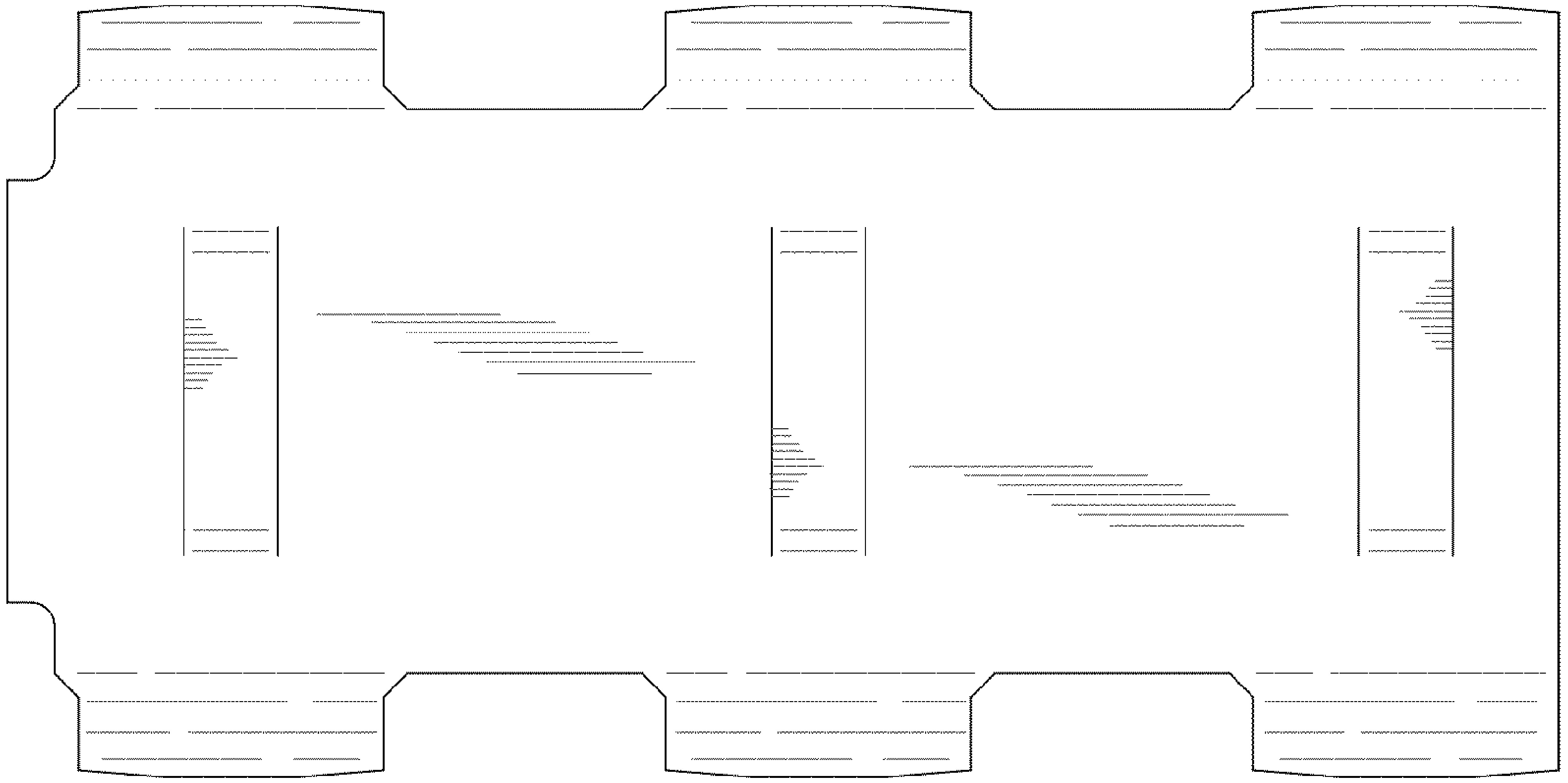


FIG.6

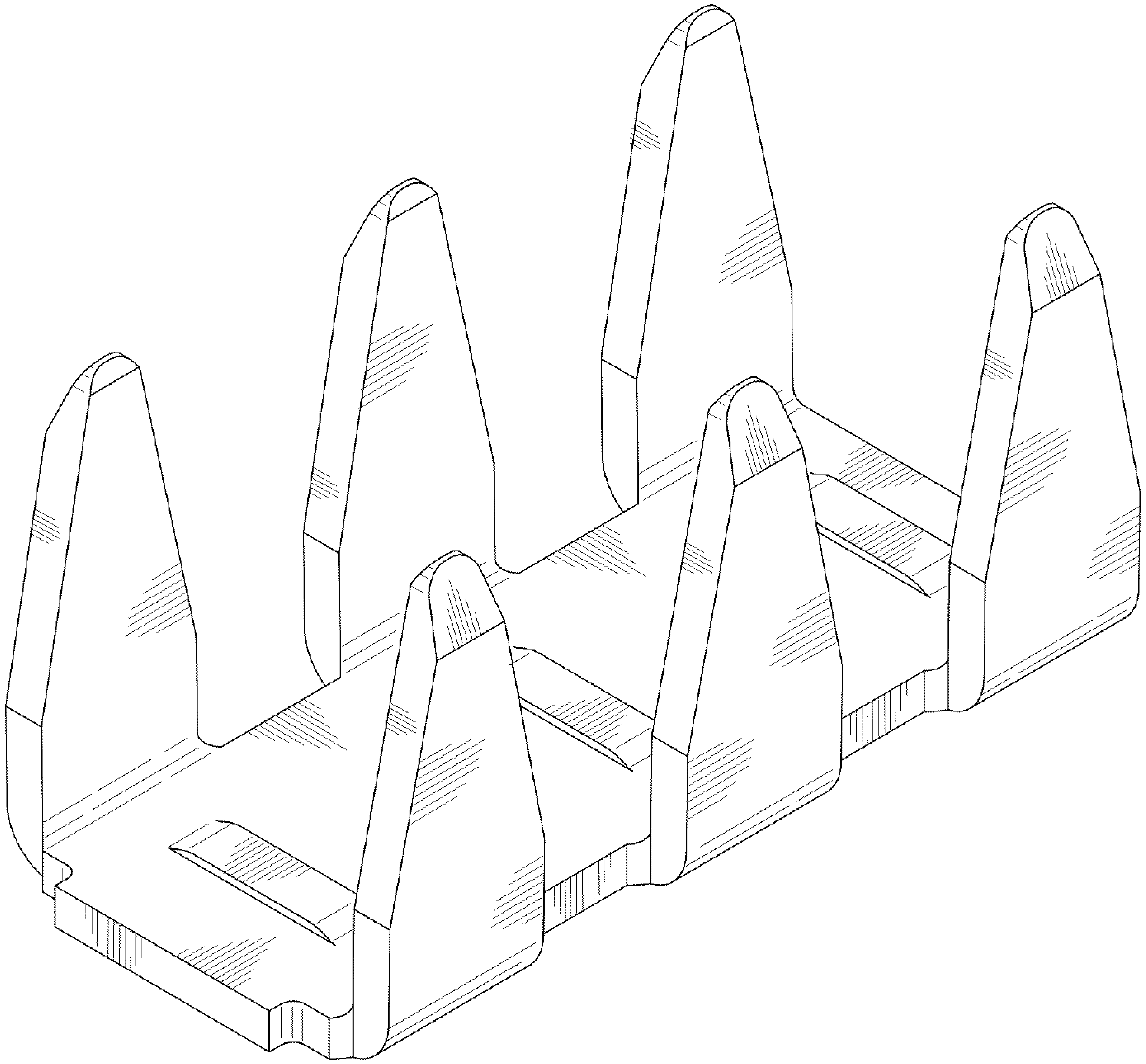


FIG.7

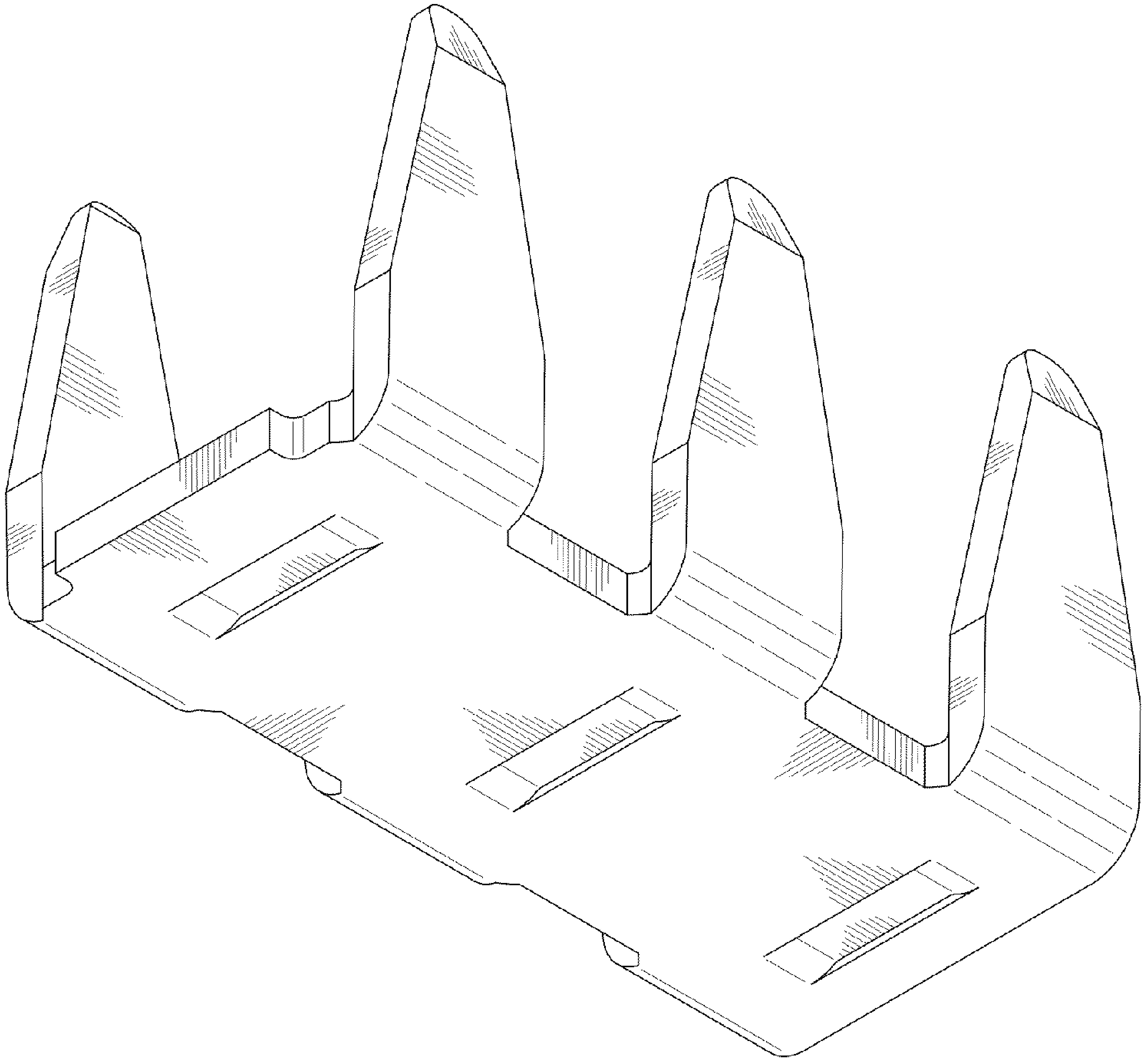


FIG.8